

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5166196

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YEN-CHUN LIU	08/20/2018
MIN-CHIAN WANG	08/20/2018
HSIANG-YEN TSAO	08/20/2018
KUO-CHAN CHIOU	08/20/2018
RECEIVING PARTY DATA	
Name:	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
Street Address:	NO. 195, SEC. 4, CHUNG HSING RD., CHUTUNG
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	31040
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16146084
CORRESPONDENCE DATA	
Fax Number:	(703)205-8050
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-205-8000
Email:	tuyen.y.ly@bskb.com, mailroom@bskb.com
Correspondent Name:	BIRCH, STEWART, KOLASCH & BIRCH, LLP
Address Line 1:	8110 GATEHOUSE ROAD, SUITE 100E
Address Line 4:	FALLS CHURCH, VIRGINIA 22042
ATTORNEY DOCKET NUMBER:	0941-3849PUS1
NAME OF SUBMITTER:	TUYEN LY
SIGNATURE:	/tuyen ly/
DATE SIGNED:	10/01/2018
Total Attachments: 2	
source=2018-09-28-ASSIGNMENT-0941-3849PUS1#page1.tif	
source=2018-09-28-ASSIGNMENT-0941-3849PUS1#page2.tif	

ASSIGNMENT

WHEREAS, Yen-Chun LIU, Min-Chian WANG, Hsiang-Yen TSAO and Kuo-Chan CHIOU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: Resin composition and method for manufacturing thermally conductive material

Filed: 09/28/2018

Serial No. 16/146,084

August 20, 2018

Executed on: _____

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chung Hsing, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Full name of sole or first inventor: Yen-Chun LIU	
Inventor's signature: <u>Yen-Chun LIU</u>	Date: <u>2018.8.20</u>

Full name of second inventor: Min-Chian WANG	
Inventor's signature: <u>Min-Chian WANG</u>	Date: <u>2018.8.20</u>

Full name of third inventor: Hsiang-Yen TSAO	
Inventor's signature: Hsiang-Yen TSAO	Date: 2018.8.20

Full name of fourth inventor: Kuo-Chan CHIOU	
Inventor's signature: 	Date: 2018.8.20